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NEWS RELEASE

Mitsui Kinzoku Rolls Out MicroThin™ for Use as Flexible PCBs

— Adapted to Thinning and Fine Pitch Assembly for High-density Mounting —

Mitsui Kinzoku Co., Ltd. (NOU Takeshi, President; hereinafter “Mitsui Kinzoku”) announces that MicroThin™, manufactured by Ageo Operation and the Malaysia Plant (Mitsui Copper Foil (Malaysia) SDN.BHD.), has begun to be introduced for flexible PCB applications.

MicroThin™, an extremely thin electrodeposited copper foil with a carrier, is a product of Mitsui Kinzoku combining a copper foil thickness ranging from 1.5 μm to 5 μm suitable for forming fine circuits, with multiple types of fine-roughening treatment. It is mainly used for semiconductor package substrates and motherboards for smartphones (HDI printed circuit boards).

Conventionally, bendability was considered important for flexible PCBs. As mobile and other devices grow more sophisticated, however, flexible PCBs rapidly thinned and fine pitch assembly became common to mount components at a high density, leading to an increase in the need for the thinnest copper foil.

Mitsui Kinzoku’s MicroThin™ utilizes the ultra-thin, high-density technologies it has accumulated for rigid PCBs and is highly regarded as a material that is able to meet the requirements regarding the formation of fine circuits on flexible PCBs and increased reliability. Already, multiple customers have introduced MicroThin™, which is produced at existing facilities, to their mass production and its application is expanding rapidly.

To meet the ever-advancing requirements in high-density mounting and high-speed communication applications, we are developing MicroThin™ for high-temperature applications compatible with various kinds of resin. By moving ahead of changes in the market and pursuing the early launch of products onto the market, we will continue to increase our competitive advantage in the electronic materials sector.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing its vision for 2030, “Building new businesses — and the future — with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

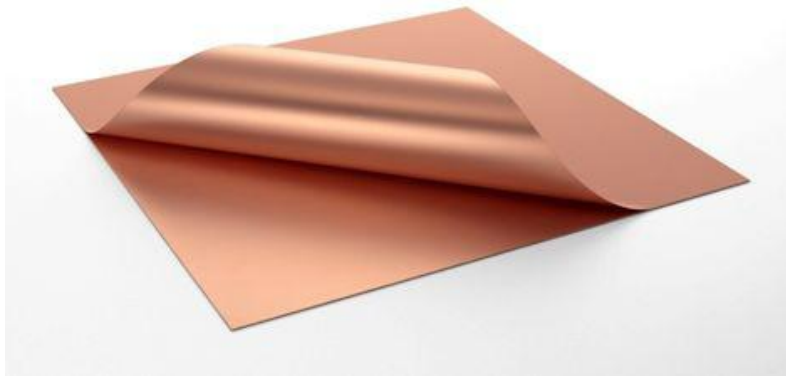
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Picture of MicroThin™



Top: Copper carrier foil (thickness: 18μm or 12μm)

Bottom: Extremely-thin copper foil (thickness: 1.5μm to 5μm)